

Security Level:

Modeling and Characterization Requirement

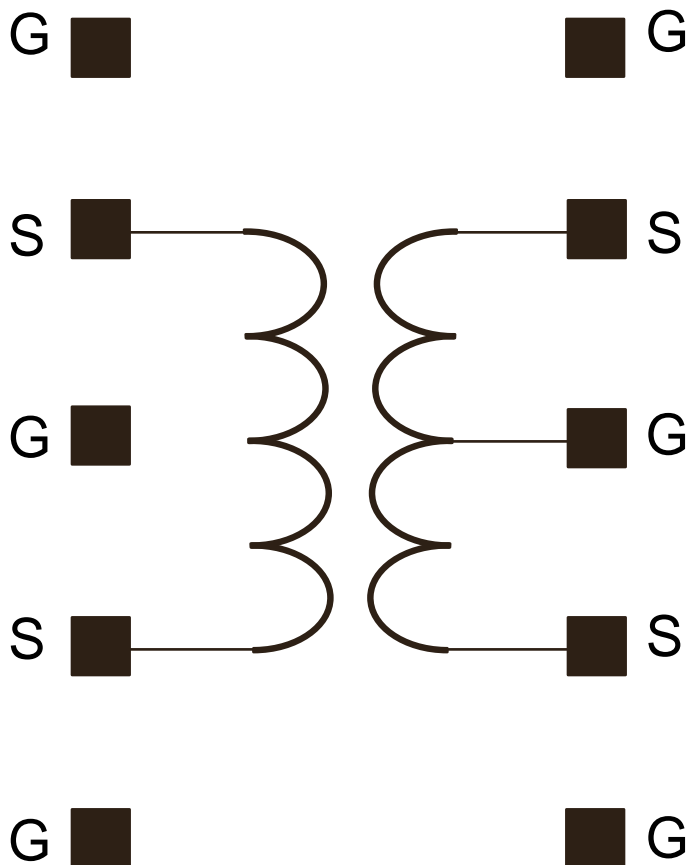
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Characterization Requirement

- 1. Characterization & modeling of baluns (x9): No issue**
 - Frequency: 0.1G~10GHz
 - Temperature: -30 ~ +125°C
 - S-parameter & Spice model for ADS & Spectre
- 2. Load pull of high power device (x2) No issue**
 - Frequency: 2.4~2.5GHz (x1) & 4.8~5.8 (x1)
 - Temperature: room temp
- 3. Characterization of 1.2V device at high DC voltage (x4) No issue**
 - Temperature: room temp
 - Id vs Vds (0~2V) plot with different Vgs(0~1.6V)
- 4. 5 samples for each of the above 5-10 sets**

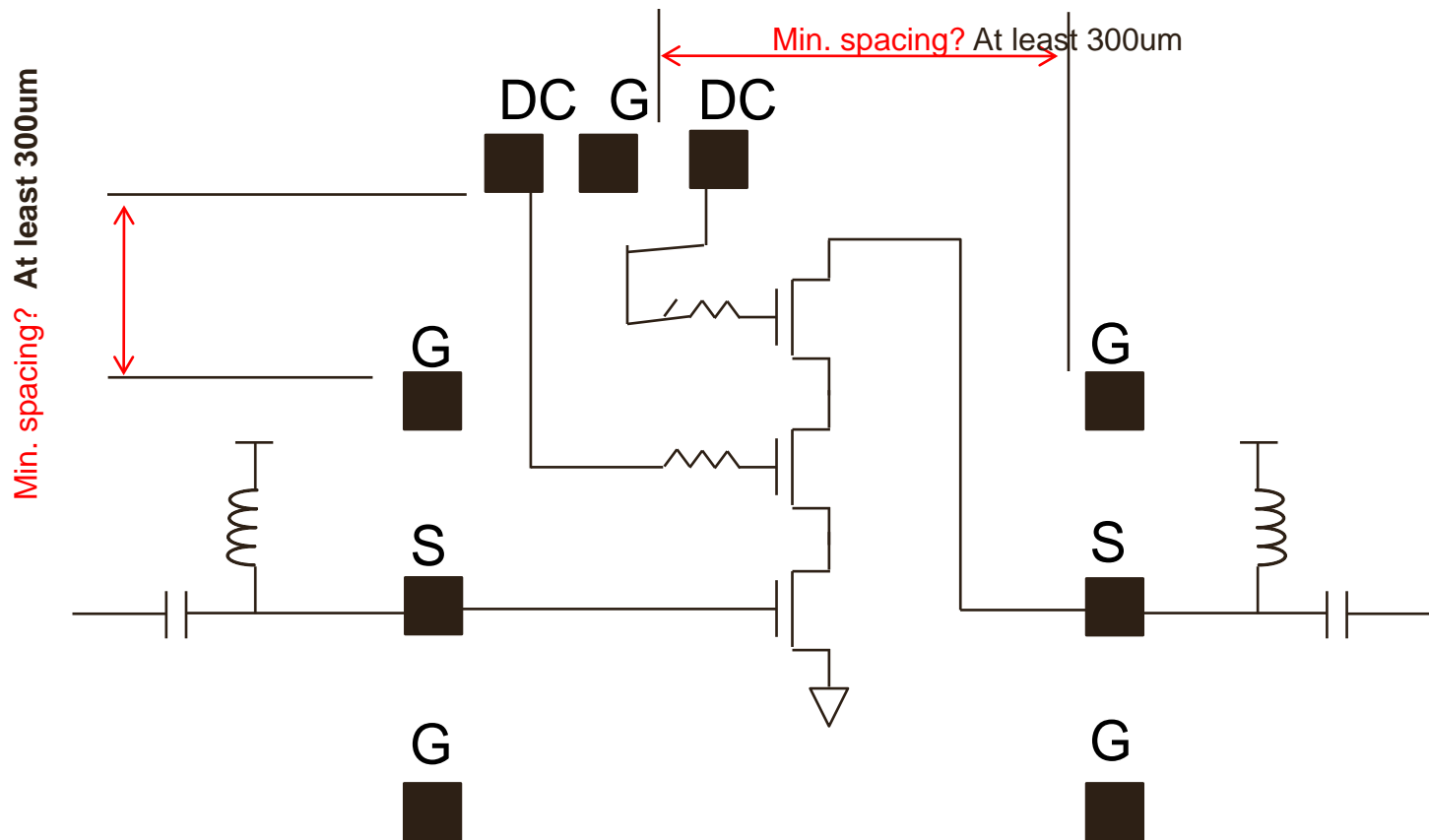
1. Characterization and Modeling of Balun



Question

- What type of de-embedding structure is required? **Thru only**
- What is the probe head pitch? 100um
- What is the min. probe pad size? **50x50um²**
- What is the probe head configuration? Eg. **GSGSG. Yes**

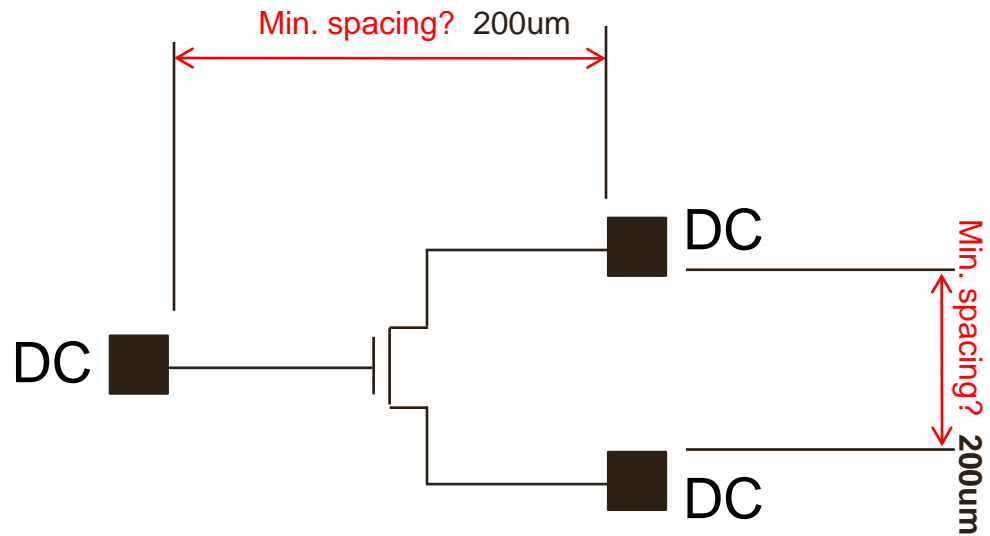
2. Load Pull of high power device



Question:

- What is the probe head pitch? **100um**
- What is the probe head configuration? Eg. **GSG** Yes for RF . For DC **PGP**.

3. Characterization of 1.2V device at high DC voltage



Thank you

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